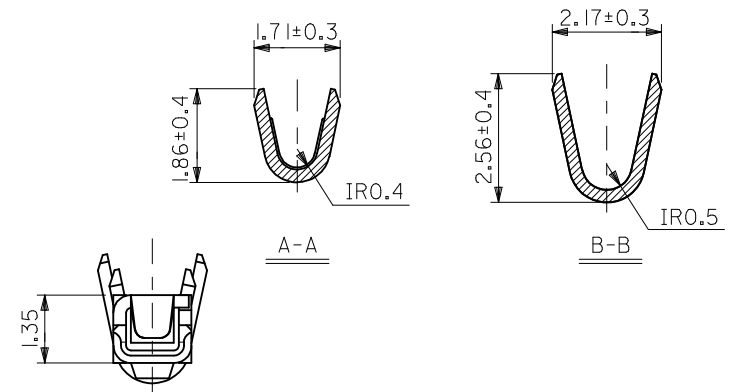


注)
NOTES

1. 材質 : りん青銅 t0.25
MATERIAL : PHOSPHOR BRONZE t0.25
2. メッキ仕様
PLATING
接点部 : 金メッキ 0.76μmMIN.
CONTACT AREA : GOLD 0.76μmMIN.
圧着部 : 半田メッキ 1.0μmMIN.
CRIMP AREA : TIN-LEAD 1.0μmMIN.
下地メッキ : ニッケルメッキ 2μmMIN.
UNDER PLATING : NICKEL 2μmMIN.
3. 適用圧着ハウジング : 51145-0601/0801
APPLICABLE CRIMP HOUSING : 51145-0601/0801
4. 適用電線範囲 : AWG #22 - #28
APPLICABLE WIRES : AWG#22 - #28
5. 被覆外径 : φ1.2mmMAX.
INSULATION O.D : φ1.2 mmMAX.
6. 適用圧着工具 (手動) : 57353-5000
APPLICABLE CRIMP TOOL (HAND) : 57353-5000
(半自動) : 57353-3000
(SEMI-AUTOMATIC) : 57353-3000
(ストリッパークリンパー) : 57353-3300
(STRIPPER CRIMPER) : 57353-3300
7. 適用引抜工具 : 57353-6000
APPLICABLE EXTRACTION TOOL : 57353-6000



連鎖状 / CHAIN	50639-8091
端子形状 / FORM	MATERIAL NO.
MODEL NO. 50639-8*91	

REVISED EC NO: J2009-1355 DRWN: NAKAMURA 2008/12/16 CHKD: T. HIRUYAMA 2008/12/16 APPR: NUKITA 2009/01/14	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY J. MIYAZAWA	DATE	TITLE 2.0MM PITCH I/O CONN. CRIMP TERMINAL	
	10 OVER 30 UNDER	±0.25	CHECKED BY Y. ITO	DATE		
	30 OVER	±0.3	APPROVED BY H. IKESUGI	DATE	MOLEX MOLEX INCORPORATED	
	ANGULAR ±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO.	DOCUMENT NO. SD-50639-003	SHEET NO. 1 OF 1	
			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		